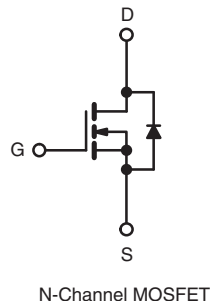
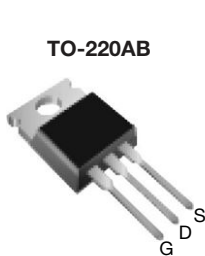


## Power MOSFET

PRODUCT SUMMARY		
$V_{DS}$ (V)	400	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10\text{ V}$	0.55
$Q_g$ (Max.) (nC)	36	
$Q_{gs}$ (nC)	9.9	
$Q_{gd}$ (nC)	16	
Configuration	Single	



### FEATURES

- Low Gate Charge  $Q_g$  Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic  $dV/dt$  Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective  $C_{OSS}$  Specified
- Compliant to RoHS Directive 2002/95/EC


**RoHS\***  
COMPLIANT

### APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptable Power Supply
- High Speed Power Switching

### TYPICAL SMPS TOPOLOGIES

- Single Transistor Flyback Xfmr. Reset
- Single Transistor Forward Xfmr. Reset (Both for US Line Input Only)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF740APbF
	SiHF740A-E3
SnPb	IRF740A
	SiHF740A


ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	$V_{DS}$	400	V	
Gate-Source Voltage	$V_{GS}$	$\pm 30$		
Continuous Drain Current	$V_{GS}$ at 10 V	$T_C = 25\text{ }^\circ\text{C}$	10	A
		$T_C = 100\text{ }^\circ\text{C}$	6.3	
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	40		
Linear Derating Factor		1.0	W/ $^\circ\text{C}$	
Single Pulse Avalanche Energy <sup>b</sup>	$E_{AS}$	630	mJ	
Repetitive Avalanche Current <sup>a</sup>	$I_{AR}$	10	A	
Repetitive Avalanche Energy <sup>a</sup>	$E_{AR}$	12.5	mJ	
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	$P_D$	125	W
Peak Diode Recovery $dV/dt^c$		$dV/dt$	5.9	V/ns
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to + 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>d</sup>	
Mounting Torque	6-32 or M3 screw		10	lbf · in
			1.1	N · m

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50\text{ V}$ , starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 12.6\text{ mH}$ ,  $R_{\theta} = 25\text{ }^\circ\text{C}$ ,  $I_{AS} = 10\text{ A}$  (see fig. 12).
- $I_{SD} \leq 10\text{ A}$ ,  $dV/dt \leq 330\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$ .
- 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	°C/W
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.50	-	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.0	

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	400	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}$	-	0.48	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	-	4.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30\text{ V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}$	-	-	25	$\mu\text{A}$
		$V_{DS} = 320\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 6.0\text{ A}^b$	-	-	0.55	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = 50\text{ V}, I_D = 6.0\text{ A}^b$	4.9	-	-	S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}, \text{ see fig. 5}$	-	1030	-	pF
Output Capacitance	$C_{oss}$		-	170	-	
Reverse Transfer Capacitance	$C_{rss}$		-	7.7	-	
Output Capacitance	$C_{oss}$	$V_{GS} = 0\text{ V}, V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$	-	1490	-	pF
		$V_{GS} = 0\text{ V}, V_{DS} = 320\text{ V}, f = 1.0\text{ MHz}$	-	52	-	
Effective Output Capacitance	$C_{oss}$	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V to } 320\text{ V}$	-	61	-	pF
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}, V_{DS} = 320\text{ V}, \text{ see fig. 6 and 13}^b$	-	-	36	nC
Gate-Source Charge	$Q_{gs}$		-	-	9.9	
Gate-Drain Charge	$Q_{gd}$		-	-	16	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 200\text{ V}, I_D = 10\text{ A}, R_g = 10\text{ }\Omega, R_D = 19.5\text{ }\Omega, \text{ see fig. 10}^b$	-	10	-	ns
Rise Time	$t_r$		-	35	-	
Turn-Off Delay Time	$t_{d(off)}$		-	24	-	
Fall Time	$t_f$		-	22	-	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	10	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$		-	-	40	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = 10\text{ A}, V_{GS} = 0\text{ V}^b$	-	-	2.0	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}, I_F = 10\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$	-	240	360	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	1.9	2.9	$\mu\text{C}$
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )				

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

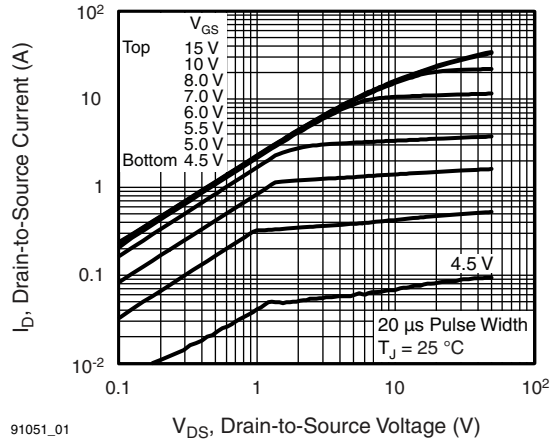


Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^\circ\text{C}$

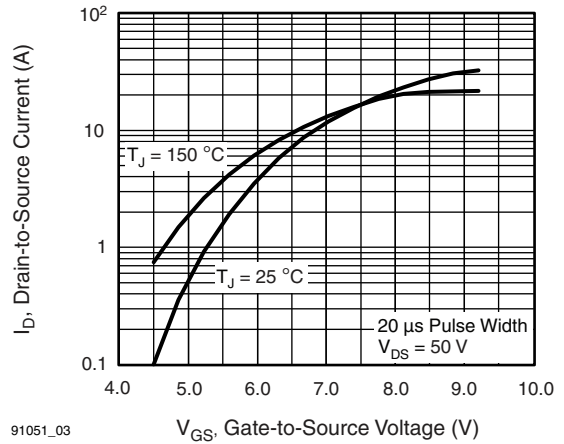


Fig. 3 - Typical Transfer Characteristics

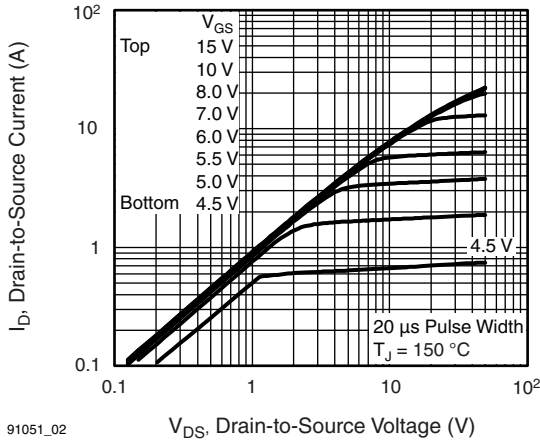


Fig. 2 - Typical Output Characteristics,  $T_C = 150\text{ }^\circ\text{C}$

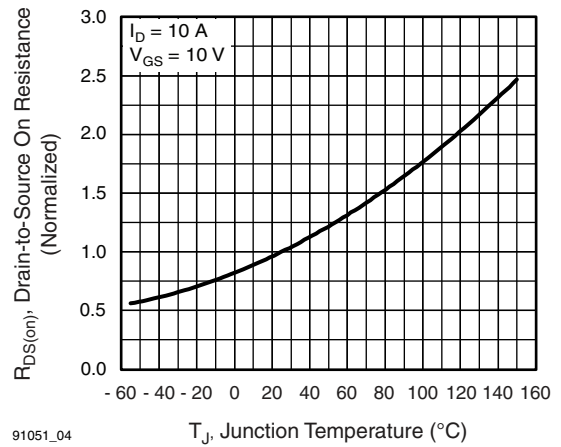
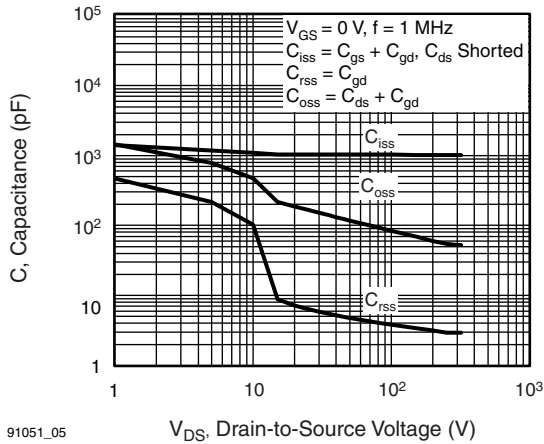
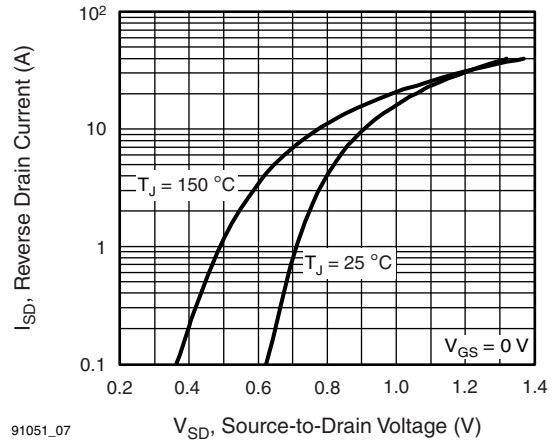


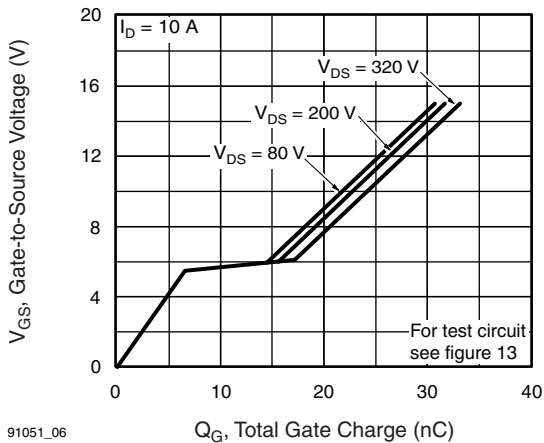
Fig. 4 - Normalized On-Resistance vs. Temperature



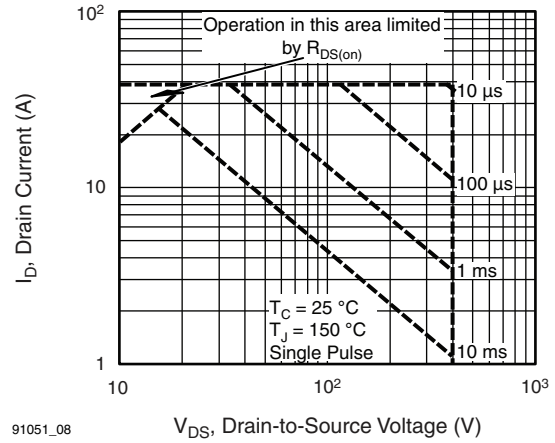
91051\_05 **Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



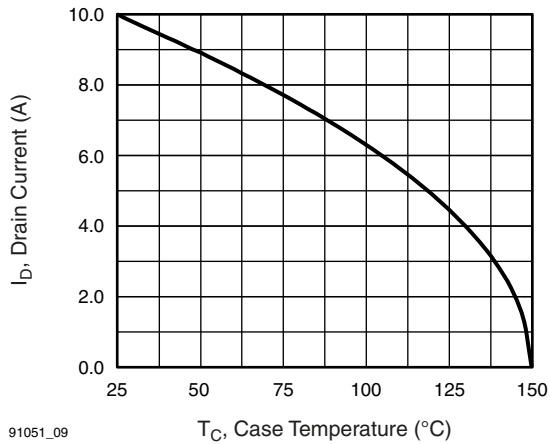
91051\_07 **Fig. 7 - Typical Source-Drain Diode Forward Voltage**



91051\_06 **Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**



91051\_08 **Fig. 8 - Maximum Safe Operating Area**



91051\_09

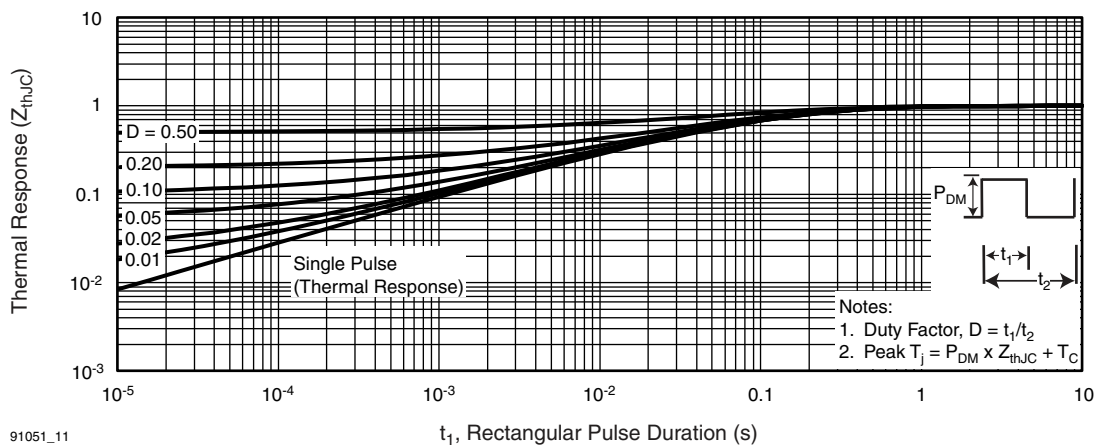
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



**Fig. 10a - Switching Time Test Circuit**

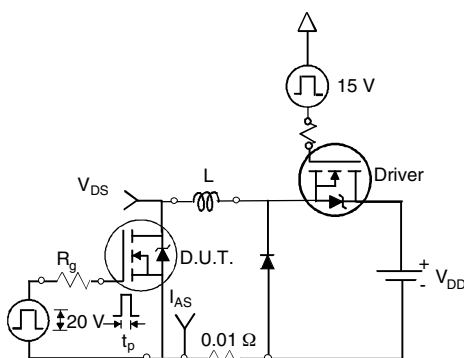


**Fig. 10b - Switching Time Waveforms**

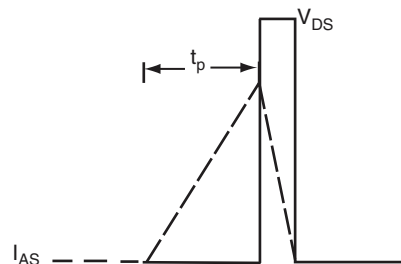


91051\_11

**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



**Fig. 12a - Unclamped Inductive Test Circuit**



**Fig. 12b - Unclamped Inductive Waveforms**

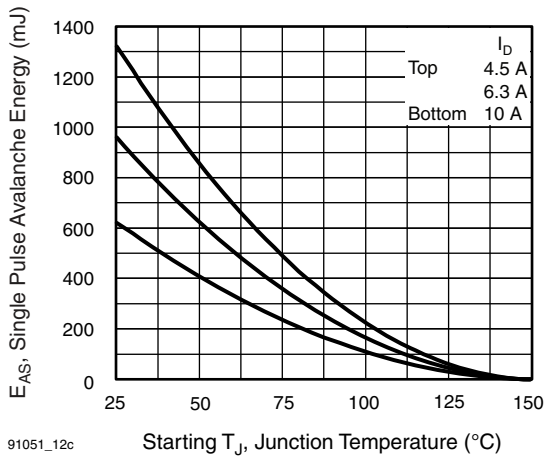


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

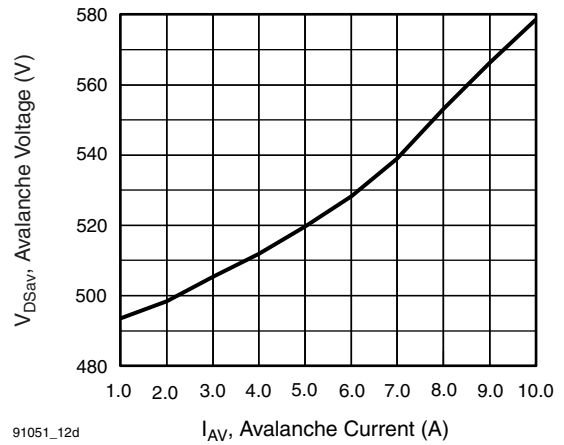


Fig. 12d - Typical Drain-to-Source Voltage vs. Avalanche Current

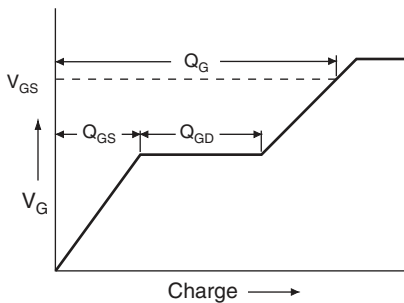


Fig. 13a - Basic Gate Charge Waveform

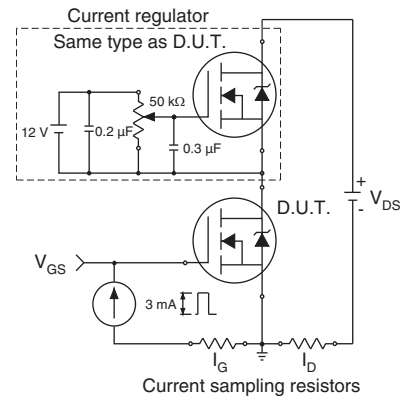
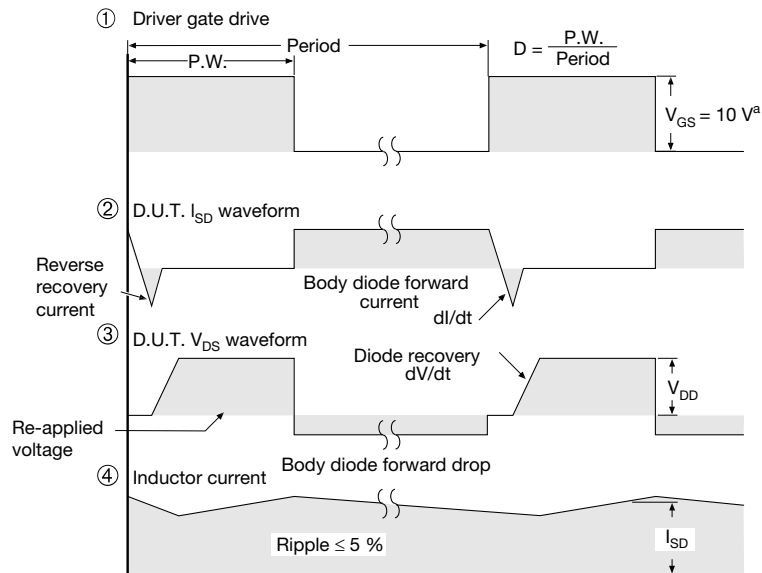
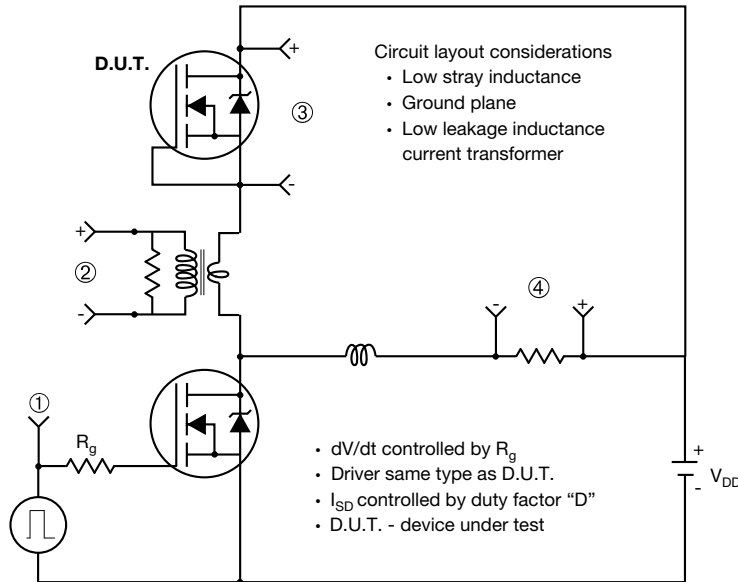


Fig. 13b - Gate Charge Test Circuit

### Peak Diode Recovery dV/dt Test Circuit



**Note**

a.  $V_{GS} = 5\text{ V}$  for logic level devices

**Fig. 14 - For N-Channel**

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TO-220AB

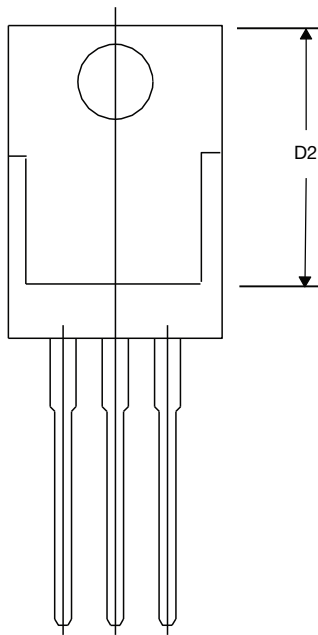


DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
c	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
$\varnothing P$	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

ECN: T14-0413-Rev. P, 16-Jun-14  
DWG: 5471

Note

\* M = 1.32 mm to 1.62 mm (dimension including protrusion)  
Heatsink hole for HVM







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